



Printed Circuit Boards  
Interconnection Carriers

**PRINTED CIRCUIT BOARDS**

01

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**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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04 108 FR4 35 L10.35 P18\_06

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

04\_108\_FR4\_35\_L10.35\_p18\_06

Layers	in $\mu$	Material	Build-Up	Assembly	
Layer-1	35 $\mu$	Copper			
	60 $\mu$	Prepreg			(60 $\mu$ PrePreg-Type: 1080)
	180 $\mu$	Prepreg			(180 $\mu$ PrePreg-Type: 7628)
	180 $\mu$	Prepreg			
Layer-2	35 $\mu$	Copper			
	100 $\mu$	L-FR4			
Layer-3	35 $\mu$	Copper			
	180 $\mu$	Prepreg			
	180 $\mu$	Prepreg			
	60 $\mu$	Prepreg			
Layer-99	35 $\mu$	Copper			